

DEVICE CLAMP FOR REDUCING OXIDATION IN WIRE BONDING

ABSTRACT

A device clamp configured for use with a wire bonding machine is provided. The device clamp includes a body portion defining at least one device aperture. Each of the at least one device apertures is configured to be positioned adjacent a bond site area of the wire bonding machine. The body portion includes a inlet port for receiving a fluid from a gas supply source. The body portion defines a fluid path from the inlet port to the at least one device aperture.

Fig. 1